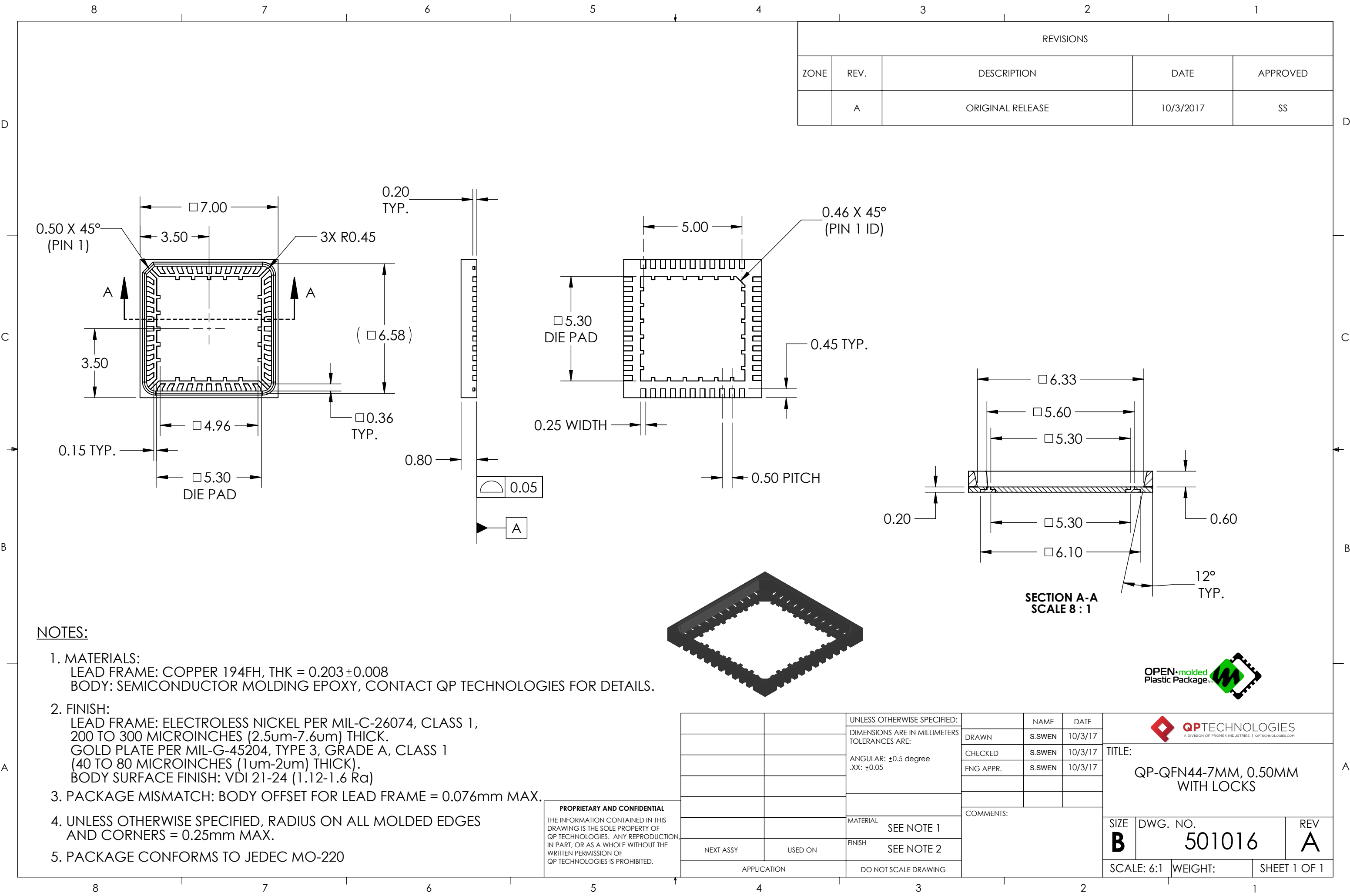




REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	10/3/2017	SS

- NOTES:**
- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QP TECHNOLOGIES FOR DETAILS.
 - FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
 - PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
 - UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
 - PACKAGE CONFORMS TO JEDEC MO-220**

PROPRIETARY AND CONFIDENTIAL
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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .XX: ±0.05		NAME	DATE	 QPTECHNOLOGIES A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM		
			DRAWN	S.SWEN	10/3/17	TITLE: QP-QFN44-7MM, 0.50MM WITH LOCKS		
			CHECKED	S.SWEN	10/3/17			
			ENG APPR.	S.SWEN	10/3/17			
			COMMENTS:			SIZE B DWG. NO. 501016 REV A		
		MATERIAL SEE NOTE 1						
NEXT ASSY	USED ON	FINISH SEE NOTE 2						
APPLICATION		DO NOT SCALE DRAWING	SCALE: 6:1 WEIGHT: SHEET 1 OF 1					

